

11017-015-01 PTO
10/06/2002
02/07/02

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

2818

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10067370	02/07/2002	438		2812	THAO LE

**APPLICANTS: Otsu Kazuhiro; Kobayashi Hideki; Sasaki Tatsuya; Ohya Kazuhiro;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

JAPAN 30746/01 02/07/2001

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no			2002-0208A
35 USC 115 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no			
Verified and Acknowledged Examiners's initials			
TITLE : Separating machine for thinned semiconductor substrate and separation method			

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
		Sheets Drwg.	Figs. Drwg.
Amount Due		Print Fig.	
Date Paid			
Primary Examiner		Application Examiner	
PREPARED FOR ISSUE			
<input type="checkbox"/> TERMINAL DISCLAIMER		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

FILED WITH:

☐ DISK (CRF)

☐ CD-ROM
(Attached in pocket on right inside flap)